

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, emplo



April 2008

FDS5351

N-Channel PowerTrench[®] MOSFET 60V, 6.1A, $35m\Omega$

Features

- Max $r_{DS(on)} = 35m\Omega$ at $V_{GS} = 10V$, $I_D = 6.1A$
- Max $r_{DS(on)} = 42m\Omega$ at $V_{GS} = 4.5V$, $I_D = 5.5A$
- High performance trench technology for extremely low r_{DS(on)}
- 100% UIL Tested
- RoHS Compliant

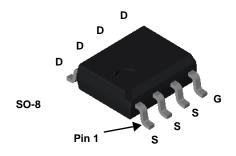


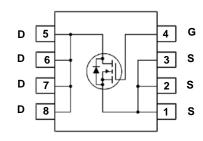
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Application

- Inverter Switch
- Synchronous Rectifier
- Load Switch





MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DS}	Drain to Source Voltage		60	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current -Continuous		6.1	^
'D	-Pulsed		30	A
E _{AS}	Single Pulse Avalanche Energy	(Note 3)	73	mJ
D	Power Dissipation T _A = 25°C	(Note 1a)	5	W
P_{D}	Power Dissipation $T_A = 25^{\circ}C$	(Note 1b)	2.5	VV
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS5351	FDS5351	SO-8	13"	12mm	2500units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted Parameter

Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250μA, referenced to 25°C		55		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 48V, V_{GS} = 0V$			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA

Test Conditions

Min

Тур

Max

Units

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.0	2.0	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, referenced to 25°C		-6.2		mV/°C
		$V_{GS} = 10V, I_D = 6.1A$		26.5	35.0	
r _{DS(on)}	r _{DS(on)} Static Drain to Source On Resistance	$V_{GS} = 4.5V, I_D = 5.5A$		32.4	42.0	mΩ
	$V_{GS} = 10V$, $I_D = 6.1A$, $T_J = 125$ °C		44.5	58.8		
g _{FS}	Forward Transconductance	$V_{DD} = 5V, I_D = 6.1A$		24		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 20V V 0V		985	1310	pF
C _{oss}	Output Capacitance	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz		90	120	pF
C _{rss}	Reverse Transfer Capacitance			50	75	pF
R_g	Gate Resistance	f = 1MHz		1.7		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	.,	8	16	ns
t _r	Rise Time	$V_{DD} = 30V, I_{D} = 6.1A,$ $V_{GS} = 10V, R_{GEN} = 6\Omega$	3	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10V, R _{GEN} = 652	21	34	ns
t _f	Fall Time		2	10	ns
Q_g	Total Gate Charge	V _{GS} = 0V to 10V	19	27	nC
Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } 4.5V$ $V_{DD} = 30V,$ $I_{D} = 6.1A$	9	13	nC
Q _{gs}	Gate to Source Charge	1 _D = 6.1A	3		nC
Q _{gd}	Gate to Drain "Miller" Charge		3.5		nC

Drain-Source Diode Characteristics

	$V_{GS} = 0V, I_S = 6.1A$	(Note 2)	0.82	1.3	\/	
V _{SD}	Source to Drain Diode Forward voltage	$V_{GS} = 0V, I_S = 2.1A$	(Note 2)	0.76	1.2	V
t _{rr}	Reverse Recovery Time			24	38	ns
Q _{rr}	Reverse Recovery Charge			15	27	nC

^{1.} R_{0,1A} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,1C} is guaranteed by design while R_{0,CA} is determined by the user's board design.



a) 50°C/W when mounted on a 1in² pad of 2 oz copper.



b) 125°C/W when mounted on a minimum pad.

- 2. Pulse Test: Pulse Width < $300\mu s$, Duty cycle < 2.0%.
- 3. UIL condition: Starting T_J = 25°C, L = 3mH, I_{AS} = 7A, V_{DD} = 60V, V_{GS} = 10V.

Typical Characteristics T_J = 25°C unless otherwise noted

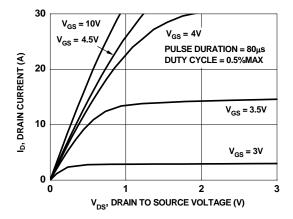


Figure 1. On-Region Characteristics

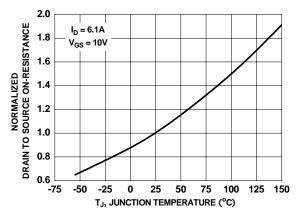


Figure 3. Normalized On-Resistance vs Junction Temperature

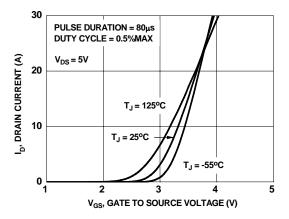


Figure 5. Transfer Characteristics

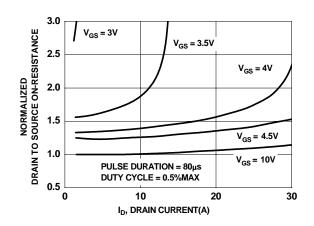


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

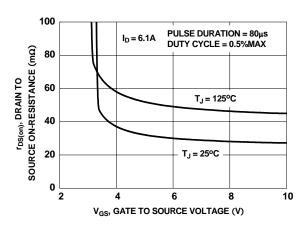


Figure 4. On-Resistance vs Gate to Source Voltage

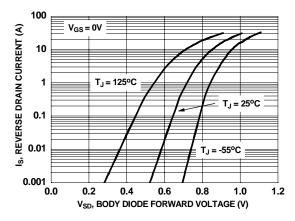


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

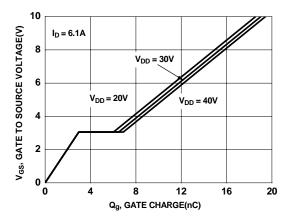


Figure 7. Gate Charge Characteristics

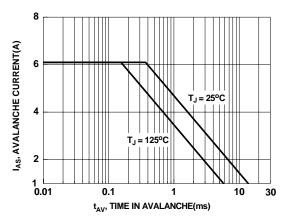


Figure 9. Unclamped Inductive Switching Capability

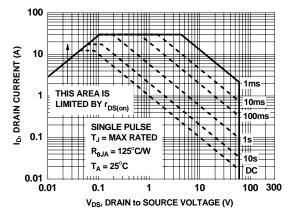


Figure 11. Forward Bias Safe Operating Area

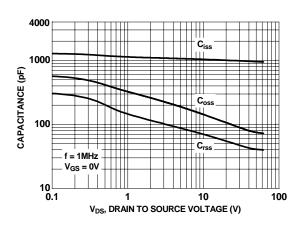


Figure 8. Capacitance vs Drain to Source Voltage

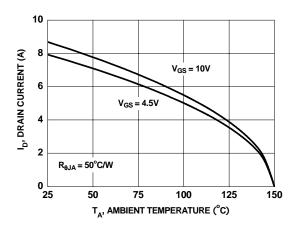


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

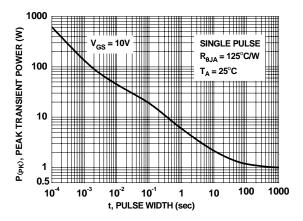


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted

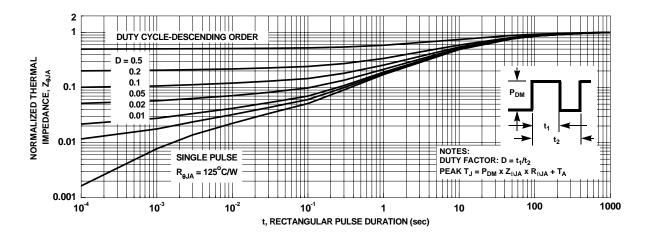


Figure 13. Transient Thermal Response Curve





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidianries, and is not intended to be an exhaustive list of all such trademarks.

			_
ACEx [®]	FPS™	PDP-SPM™	The Power Franchise®
Build it Now™	F-PFS™	Power-SPM™	puwer
CorePLUS™	FRFET®	PowerTrench®	p wer franchise
CorePOWER™	Global Power Resource SM	Programmable Active Droop™	TinyBoost™
CROSSVOLT™	Green FPS™	QFET [®]	TinyBuck™
CTL™	Green FPS™ e-Series™	QS™	TinyLogic [®]
Current Transfer Logic™	GTO™	Quiet Series™	TINYOPTO™
EcoSPARK [®]	IntelliMAX™	RapidConfigure™	TinyPower™
EfficentMax™	ISOPLANAR™	Saving our world 1mW at a time™	TinyPWM™
EZSWITCH™ *	MegaBuck™	SmartMax™	TinyWire™
E Z. TM	MICROCOUPLER™	SMART START™	μSerDes™
	MicroFET™	SPM [®]	W
₽ ®	MicroPak™	STEALTH™	Ser Des
Fairchild [®]	MillerDrive™	SuperFET™	UHC [®]
Fairchild Semiconductor®	MotionMax™	SuperSOT™-3	Ultra FRFET™
FACT Quiet Series™	Motion-SPM™	SuperSOT™-6	UniFET™
FACT [®]	OPTOLOGIC [®]	SuperSOT™-8	VCX TM
FAST [®]	OPTOPLANAR [®]	SuperMOS™	VisualMax™
FastvCore™	®	SYSTEM ®	
FlashWriter [®] *	<u></u>	GENERAL	

^{*} EZSWITCH™ and FlashWriter® are trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which,

 (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I34

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative